



## Declaration

I, Kumiko Lancet, declare that I am well acquainted with English and Japanese languages and that I have carefully translated the attached English language translations from the original documents, entitled

半導体封止用樹脂組成物及びそれを用いた半導体装置

Japanese Patent Application Kokai No. H11-100492 [Resin Composition for Encapsulating Semiconductors, and the Semiconductor Device That Uses this Composition]

written in Japanese and that the attached translation is an accurate English version of such original to the best of my knowledge and belief.

Date 3/27/2006

*Kumiko Lancet*

Name Kumiko Lancet

Address 2254 Clairmont Dr.  
Pittsburgh, PA 15241